Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-12. (Canceled)

13. (New) A semiconductor device comprising:

a substrate;

at least one output bit group, comprising a plurality of first output patterns, provided on the substrate and configured such that each of the first output patterns is continuously arrayed; and

a dummy pattern, comprising at least one second output pattern having the same shape as each of the first output patterns, the dummy pattern provided on the substrate and being adjacent to an end portion of the output bit group.

14. (New) A semiconductor device for a driver comprising:

a substrate;

at least one output bit group, comprising a plurality of first output patterns, provided on the substrate and configured such that each of the first output patterns is continuously arrayed, each of the first output patterns corresponding to one bit; and

a dummy pattern, comprising at least one second output pattern having the same shape as each of the first output patterns, the dummy pattern provided on the substrate and being adjacent to an end portion of the output bit group.

15. (New) The semiconductor device according to claim 14, wherein the dummy pattern and the output bit group is arrayed in a straight line.

16. (New) The semiconductor device according to claim 14, wherein a plurality of the output bit groups are provided on the substrate, and the output groups constitute, respectively, a cathode driver, an anode driver, and an anode driver for icon.

17. (New) The semiconductor device according to claim 14, wherein a number of the second output patterns provided in an area where each of the output bit groups is adjacent to each other is less than a number of the second output patterns provided in an area where each of the output bit groups is not adjacent to each other.

18. (New) The semiconductor device according to claim 14, wherein the second output pattern has the same shape as wiring for a gate electrode.

19. (New) The semiconductor device according to claim 14, wherein each second output pattern has the same two-dimensional shape as the first output patterns when viewed from above.

20. (New) A method for forming a pattern layout of a semiconductor device, comprising:

providing a substrate;

providing on the substrate at least one output bit group comprising a plurality of first output patterns and configured such that each of the first output patterns is continuously arrayed; and

providing on the substrate a dummy pattern comprising at least one second output pattern having the same shape as each of the first output patterns and being adjacent to an end portion of the output bit group.

21. (New) A method for forming a pattern layout of semiconductor device for a driver comprising:

providing a substrate;

providing on the substrate at least one output bit group comprising a plurality of first output patterns and configured such that each of the first output patterns is continuously arrayed, each of the first output patterns corresponding to one bit; and

providing on the substrate a dummy pattern comprising at least one second output pattern having the same shape as each of the first output patterns and being adjacent to an end portion of the output bit group.

22. (New) The method for forming a pattern layout of a semiconductor device for a driver according to claim 21, wherein the dummy pattern and the output bit group is arrayed in a straight line.

23. (New) The method for forming a pattern layout of a semiconductor device for a driver according to claim 21, wherein a plurality of the output bit groups are provided on the substrate, wherein the output groups constitute, respectively, a cathode driver, an anode driver, and an anode driver for icon.

24. The method for forming a pattern layout of a semiconductor device for a driver according to claim 21, wherein a number of the second output patterns provided in an area where each of the output bit groups is adjacent to each other is less than a number of the second output patterns provided in an area where each of the output bit groups is not adjacent to each other.

25. The method for forming a pattern layout of a semiconductor device for a driver according to claim 21, wherein the second output pattern has the same shape as wiring for a gate electrode.

26. (New) The method for forming a pattern layout of a semiconductor device for a driver according to claim 21, wherein each second output pattern has the same two-dimensional shape, when viewed from above, as the first output patterns.